



## Material Content Data Sheet



<b>Sales Product Name</b>		BFR 340F H6327		<b>Issued</b>		24. January 2018		
<b>MA#</b>		MA001305756						
<b>Package</b>		PG-TSFP-3-1		<b>Weight*</b>		1.43 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.03		324	
	noble metal	gold	7440-57-5	0.002	0.13		1258	
	inorganic material	silicon	7440-21-3	0.016	1.09	1.25	10859	12441
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		80	
	non noble metal	titanium	7440-32-6	0.001	0.04		400	
	non noble metal	chromium	7440-47-3	0.002	0.12		1199	
	non noble metal	copper	7440-50-8	0.570	39.79	39.96	397866	399545
wire	noble metal	gold	7440-57-5	0.004	0.27	0.27	2713	2713
	encapsulation	organic material	carbon black	1333-86-4	0.008	0.54		5446
plastics		epoxy resin	-	0.168	11.71		117083	
inorganic material		silicondioxide	60676-86-0	0.605	42.19	54.44	422044	544573
leadfinish	non noble metal	tin	7440-31-5	0.033	2.34	2.34	23353	23353
plating	noble metal	silver	7440-22-4	0.025	1.74	1.74	17375	17375
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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